

Flash Memory Summit

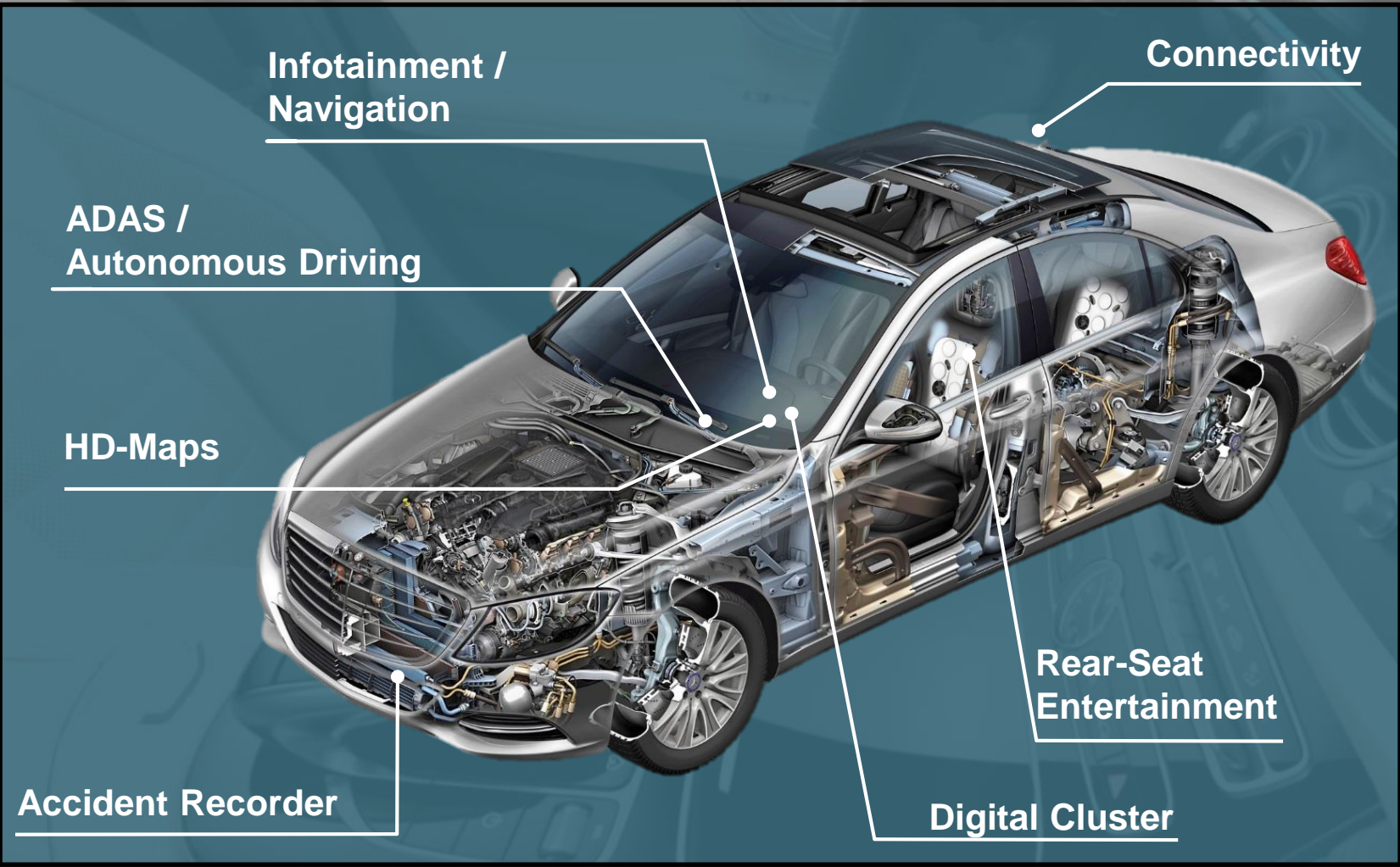
# Requirements for Non-volatile Memory in Automotive Applications






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Santa Clara CA, August 2017

Mercedes-Benz  
The best or nothing.



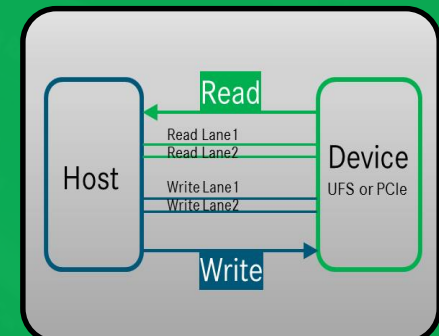
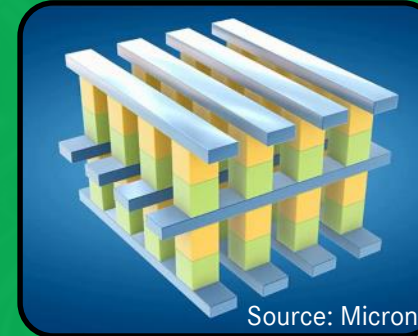
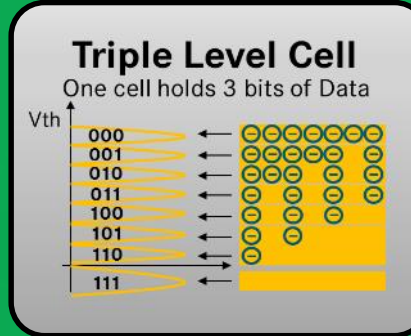
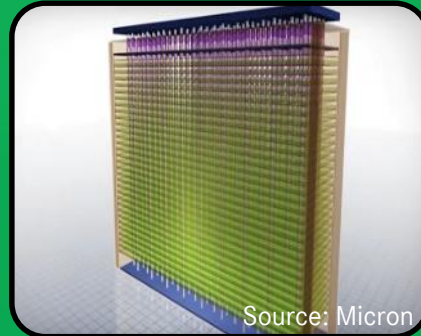
# NVM Storage in Infotainment



	Infotainment	64 - 512 GB
	Digital Cluster	4 - 32 GB
	Rear-Seat Entertainment	16 - 64 GB
	Connectivity	4 - 16 GB
	ADAS / Autonomous Driving	8 - 16 GB
	HD-Maps	8 - 512 GB
	Accident recording	8-64 GB

In 2025 on board storage >1TB

# Our View on NVM Memory Trends in Infotainment



## Flash technology replaces HDD

Higher Speed  
Almost same cost  
Mainstream technology

## 3D-Cell Technology

Cell shrink stopped in 2D planar technology  
Capacity increase only possible with 3D technology

## Triple Level Cell Technology

3D allow more electrons per cell  
Capacity per die increases  
Price advantage over planar technology

## Persistent Memory

New memories: X-Point, SCM and MRAM  
No endurance problem  
BUT: Reliability not yet proven

## Emerging NVM Interfaces

eMMC bandwidth no longer sufficient  
Move to serial high speed Interfaces: UFS or PCIe

# Requirements of Infotainment Systems on Flash Memory



## Fast System Startup

High Read Speed: New interfaces UFS, PCIe  
Short initialization time after power up



## Early Adoption of New Technology

No time gap between Automotive and CE  
Latest technology: 15 nm planar, 3D, TLC



## Quality

Quality: 0 ppm target, 8d reports  
Mercedes-Benz MBN-10527 Specification  
2<sup>nd</sup> source with standard interfaces



## Energy Efficiency

Limited system cooling capacity  
Shared power budget for SoC, RAM, Flash Memory, Amplifier, Interfaces, etc.



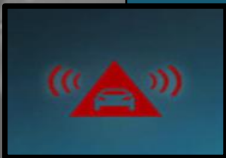
## Robustness / Endurance

Power fail save  
Temperature -40..+105 °C  
Data Retention for years/months



## Scalability

Memory sizes between 4 GB and 512 GB  
Read/Write Bandwidth options 1 – 4 Lanes



## Diagnosis

Health status of the device  
Available write budget



## Package space

Direct mounted components (BGA)

# Generic Development Schedule and Steps

Advanced Engineering

Series Development

Request for Information

Architecture Phase

Request for Quotation  
Project Award

Project Start

Initial Sample Inspection  
Report (ISIR)

SOP

Duration

3 - 6  
Month

6 - 12  
Month

18 - 24  
Month

10  
Month

## Electronic component schedule

Sample Level	Months before SOP
Working	30
Engineering	24
Fully Qualified	18

# Example for extended Automotive Requirements: UFS Diagnosis

## Specific Functions for Automotive Applications required

Every part in our system has to be diagnosed and we need detailed information about the device health status.

Diagnosis is used for:

- Development
- Field diagnosis
- Failure analysis

→ JEDEC diagnosis standard is not enough

→ **Common extended diagnosis commands among memory vendors needed**

## Extract of required Diagnosis commands

### On/Off Statistics

- Power on cycles
- Power on repairs

### Refresh strategy

- Refresh status
- Set refresh strategy

### Flash profiling

- Erase count, max. erase, total Block read/write
- Wear level prediction

### Error logging

- Interface errors
- ECC level

# Quality Requirement: MBN-10527



## Environment: Car

**80%** of the innovations driven by **semiconductors**

Number of Semiconductor devices grow rapidly

Long lifetime of unit

Harsh environment: Thermal shock, Temperature from  $-40..+80^{\circ}\text{C}$ , Vibration, Long periods without power

Parameter	Consumer	Industrial	Automotive
Temperature	0 - 40 °C	-10 - 70°C	-40 - 160°C
Operation Time	2 - 5 years	5 -10 years	> 15 years
Humidity	Low	Environment	0 % - 100 %
Field Failure Rate	< 10 %	<< 1 %	0 ppm Target
Documentation	Minimal	Conditional	PPAP, 8D, PCN Management
Supply	Average 1 year	~ 2- 5 years	Up to 15 years

## Targets for MBN-10527

Comparison of semiconductor manufacturers

Reduce semiconductor related design/quality/reliability/supply issues

MBN-10527 includes ISO/TS 16949 and AEC-Q

# Summary

- Automotive development cycles vs. early technology adoption
  - Working/Engineering Samples 30/24M before SOP
  - Robust supply of components for whole product lifetime of 15Y
  - Long-established technologies not acceptable for new systems
  - Most advanced performance and capacity required for every car generation
- Paradigm shift towards Automotive Industry as technology driver
- Automotive Requirements beyond consumer standard
  - E.g. for diagnosis extensions necessary
- Storage Demand in Automotive is rapidly growing